

## CLAIMS

What is claimed is:

- 1 1. An apparatus comprising:
  - 2 a printed circuit board (PCB);
  - 3 a connector mounted on the PCB; and
  - 4 an integrated circuit (IC) package for insertion into the connector, the IC
  - 5 package having a plurality of lands with a varied pitch distance.
- 1 2. The apparatus of claim 1 wherein the plurality of lands include a vertical  
2 pitch having a first distance and a horizontal pitch having a second distance.
- 1 3. The apparatus of claim 1 wherein the connector includes a plurality of  
2 contacts having a varied pitch distance to match the plurality of lands.
- 1 4. The apparatus of claim 3 wherein the PCB comprises a plurality of land  
2 pads having a varied pitch distance to match the plurality of contacts.
- 1 5. The apparatus of claim 4 wherein the PCB comprises a plurality of traces  
2 coupled to the plurality of land pads.
- 1 6. The apparatus of claim 1 wherein the PCB is a motherboard.
- 1 7. The apparatus of claim 1 wherein the connector is a zero insertion force  
2 (ZIF) connector.

1 8. The apparatus of claim 1 wherein the IC package is a land grid array  
2 (LGA).

1 9. An apparatus comprising:  
2 a printed circuit board (PCB);  
3 a connector mounted on the PCB; and  
4 an integrated circuit (IC) package for insertion into the connector, the IC  
5 package having a plurality of pins with a varied pitch distance.

1 10. The apparatus of claim 9 wherein the plurality of pins include a vertical  
2 pitch having a first distance and a horizontal pitch having a second distance.

1 11. The apparatus of claim 10 wherein the PCB comprises a plurality of pin  
2 pads having a varied pitch distance to match the plurality of pins.

1 12. The apparatus of claim 9 wherein the IC package is a pin grid array  
2 (PGA).

1 13. An integrated circuit (IC) comprising:  
2 one or more logic elements; and  
3 a plurality of input/output pins (I/O) connectors, coupled to the one or  
4 more logic elements, having a varied pitch distance.

1 14. The IC of claim 13 wherein the plurality of I/O connectors include a

2 vertical pitch having a first distance and a horizontal pitch having a second  
3 distance.

1 15. The IC of claim 13 wherein the plurality of I/O connectors comprise lands.

1 16. The IC of claim 13 wherein the plurality of I/O connectors comprise pins.